



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-09
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H742IIK6	28MR*450XXXV	A	9991	2025-04-09
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	104	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	10x10	201	Bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	28MR*450XXXV		104.0005		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.125	mg	supplier	die	Silicon (Si)	7440-21-3		3.930	mg	952729	37788.35
				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	5606	222.35
				supplier	metallization	Copper (Cu)	7440-50-8		0.073	mg	17583	697.40
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	64	2.54
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	2867	113.71
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	510	20.23
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	64	2.54
				supplier	Passivation	Silicon Oxide	7631-86-9		0.085	mg	20577	816.15
				supplier	Substrate	Barium Sulfate	7727-43-7		2.411	mg	60000	23182.49
Substrate (A25621)	Copper & its alloys	40.183	mg	supplier	Substrate	Silica	7631-86-9		0.402	mg	10000	3863.75
				supplier	Substrate	Talc	14807-96-6		0.402	mg	10000	3863.75
				supplier	Substrate	Dipropylene Glycol Monomethyl Ether	34590-94-8		1.205	mg	30000	11591.24
				supplier	Substrate	Epoxy Resin	85954-11-6		1.205	mg	30000	11591.24
				supplier	Substrate	Cured thermosetting resin	Proprietary		1.607	mg	40000	15454.99
				supplier	Substrate	Continuous Filament Fiber Glass	65997-17-3		10.046	mg	250000	96593.69
				supplier	Substrate	Copper (Cu)	7440-50-8		18.082	mg	450000	173868.64
				supplier	Substrate	Nickel (Ni)	7440-02-0		3.616	mg	90000	34773.73
				supplier	Substrate	Gold (Au)	7440-57-5		1.205	mg	30000	11591.24
DAF (ATB-125-12)	Precious metals	5.910	mg	supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-termina	68610-41-3		3.842	mg	650000	36937.32
				supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxiran	37382-79-9		1.478	mg	250000	14206.66
				supplier	Glue or tape	Dapsone	80-08-0		0.355	mg	60000	3409.60
				supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.118	mg	20000	1136.53
				supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin); e	25068-38-6		0.118	mg	20000	1136.53
Bonding wire (Cu)	Precious metals	2.400	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.317	mg	965500	22279.15
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.074	mg	31000	715.33
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.008	mg	3500	80.76
Encapsulation (KE-G1250AAS)	Other inorganic materials	46.495	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0		44.170	mg	950000	424707.30
				supplier	Molding Compound	Epoxy resin	Proprietary		1.046	mg	22500	10058.86
				supplier	Molding Compound	Phenol resin	Proprietary		1.046	mg	22500	10058.86
				supplier	Molding Compound	Carbon Black	1333-86-4		0.232	mg	5000	2235.30
Solder Balls (96.5Sn3.5Ag)	Other Nonferrous metals & alloys	4.888	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		4.717	mg	965000	45354.78
				supplier	Matte Sn	Silver (Ag)	7440-22-4		0.171	mg	35000	1644.99